

# CY7C164 CY7C166

#### Features

- High speed — 15 ns
- Output enable (OE) feature (7C166)
- CMOS for optimum speed/power
- Low active power
  - —633 mW
- · Low standby power
  - —220 mW
- TTL-compatible inputs and outputs
- Automatic power-down when deselected

#### **Functional Description**

The CY7C164 and CY7C166 are high-performance CMOS static RAMs organized as 16,384 by 4 bits. Easy memory expansion is provided by an active LOW chip enable ( $\overline{CE}$ ) and

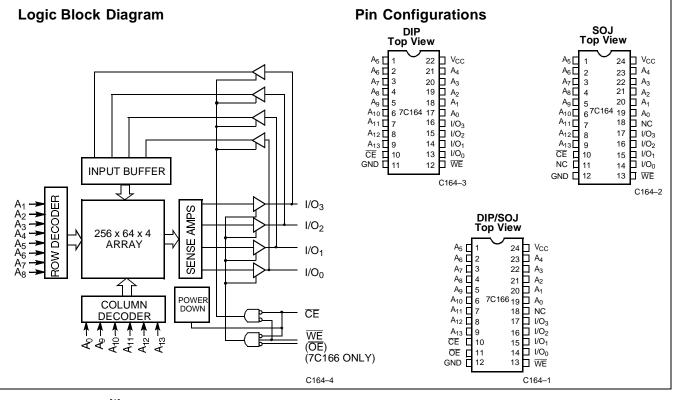
# 16K x 4 Static RAM

three-state drivers. The CY7C166 has an active low output enable ( $\overline{\text{OE}}$ ) feature. Both devices have an automatic power-down feature, reducing the power consumption by 65% when deselected.

Writing to the device is accomplished when the chip enable  $(\overline{CE})$  and write enable  $(\overline{WE})$  inputs are both LOW (and the output enable  $(\overline{OE})$  is LOW for the 7C166). Data on the four input/output pins (I/O0 through I/O3) is written into the memory location specified on the address pins (A0 through A13).

Reading the device is accomplished by taking chip enable  $(\overline{CE})$  LOW (and  $\overline{OE}$  LOW for 7C166), while write enable ( $\overline{WE}$ ) remains HIGH. Under these conditions the contents of the memory location specified on the address pins will appear on the four data I/O pins.

The I/O pins stay in a high-impedance state when chip enable  $(\overline{CE})$  is HIGH (or output enable  $(\overline{OE})$  is HIGH for 7C166). A die coat is used to insure alpha immunity.



#### Selection Guide<sup>[1]</sup>

	7C164-12 7C166-12	7C164-15 7C166-15	7C164-20 7C166-20	7C164-25 7C166-25	7C164-35 7C166-35
Maximum Access Time (ns)	12	15	20	25	35
Maximum Operating Current (mA)	160	115	80	70	70
Maximum Standby Current (mA)	40/20	40/20	40/20	20/20	20/20

Shaded area contains advanced information.

1. For military specifications, see the CY6C164A/CY7C166A datasheet

Note:



# **Maximum Ratings**

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature65°C to +150°C
Ambient Temperature with Power Applied55°C to +125°C
Supply Voltage to Ground Potential0.5V to +7.0V
DC Voltage Applied to Outputs in High Z State <sup>[2]</sup> 0.5V to +7.0V
DC Input Voltage <sup>[2]</sup> 0.5V to +7.0V

Output Current into Outputs (LOW)	20 mA
Static Discharge Voltage (per MIL-STD-883, Method 3015)	>2001V
Latch-Up Current	>200 mA

#### **Operating Range**

Range	Ambient Temperature	v <sub>cc</sub>
Commercial	0°C to +70°C	5V ± 10%

#### Electrical Characteristics Over the Operating Range

				7C164-12 7C166-12		7C164-15 7C166-15		64-20 66-20	7C164-25, 35 7C166-25, 35		
Parameter	Description	Test Conditions	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Unit
V <sub>OH</sub>	Output HIGH Voltage	V <sub>CC</sub> = Min., I <sub>OH</sub> = -4.0 mA	2.4		2.4		2.4		2.4		V
V <sub>OL</sub>	Output LOW Voltage	V <sub>CC</sub> = Min., I <sub>OL</sub> = 8.0 mA		0.4		0.4		0.4		0.4	V
V <sub>IH</sub>	Input HIGH Voltage		2.2	V <sub>CC</sub>	2.2	V <sub>CC</sub>	2.2	V <sub>CC</sub>	2.2	V <sub>CC</sub>	V
V <sub>IL</sub>	Input LOW Voltage <sup>[2]</sup>		-0.5	0.8	-0.5	0.8	-0.5	0.8	-0.5	0.8	V
I <sub>IX</sub>	Input Load Current	$GND \le V_I \le V_{CC}$	-5	+5	-5	+5	-5	+5	-5	+5	μΑ
I <sub>OZ</sub>	Output Leakage Current	GND ≤ V <sub>O</sub> ≤ V <sub>CC</sub> , Output Disabled	-5	+5	-5	+5	-5	+5	-5	+5	μA
I <sub>OS</sub>	Output Short Circuit Current <sup>[3]</sup>	V <sub>CC</sub> = Max., V <sub>OUT</sub> = GND		-350		-350		-350		-350	mA
I <sub>CC</sub>	V <sub>CC</sub> Operating Supply Current	V <sub>CC</sub> = Max., I <sub>OUT</sub> = 0 mA		160		115		80		70	mA
I <sub>SB1</sub>	Automatic CE Power-Down Current <sup>[4]</sup>	Max. V <sub>CC</sub> , <u>CE</u> ≥ V <sub>IH,</sub> Min. Duty Cycle = 100%		40		40		40		20	mA
I <sub>SB2</sub>	Automatic CE Power-Down Current <sup>[4]</sup>	$\begin{array}{l} \underset{CE}{Max.} V_{CC}, \\ \hline CE \geq V_{CC} - 0.3V, \\ V_{IN} \geq V_{CC} - 0.3V \\ or V_{IN} \leq 0.3V \end{array}$		20		20		20		20	mA

Shaded area contains advanced information.

## Capacitance<sup>[5]</sup>

Parameter	Description	Test Conditions	Max.	Unit
C <sub>IN</sub>	Input Capacitance	$T_A = 25^{\circ}C, f = 1 \text{ MHz},$	10	pF
C <sub>OUT</sub>	Output Capacitance	$V_{CC} = 5.0V$	10	pF

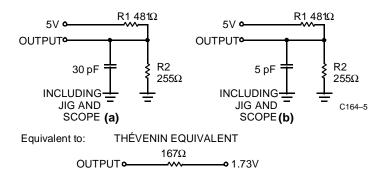
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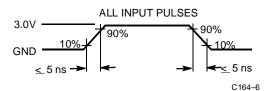
2. 3. 4. 5.

Minimum voltage is equal to -3.0V for pulse durations less than 30 ns. Not more than 1 output should be shorted at one time. Duration of the short circuit should not exceed 30 seconds. A pull-up resistor to V<sub>CC</sub> on the CE input is required to keep the device deselected during V<sub>CC</sub> power-up, otherwise I<sub>SB</sub> will exceed values given. Tested initially and after any design or process changes that may affect these parameters.



## **AC Test Loads and Waveforms**





#### Switching Characteristics Over the Operating Range<sup>[6]</sup>

	Description			64-12 66-12		64-15 66-15		64-20 66-20		64-25 66-25		64-35 66-35	
Parameter			Min.	Max.	Unit								
READ CYC	LE												
t <sub>RC</sub>	Read Cycle Time		12		15		20		25		35		ns
t <sub>AA</sub>	Address to Data Valid			12		15		20		25		35	ns
t <sub>OHA</sub>	Output Hold from Addres Change	s	3		3		5		5		5		ns
t <sub>ACE</sub>	CE LOW to Data Valid			12		15		20		25		35	ns
t <sub>DOE</sub>	OE LOW to Data Valid	7C166		6		10		10		12		15	ns
t <sub>LZOE</sub>	OE LOW to Low Z	7C166	0		3		3		3		3		ns
t <sub>HZOE</sub>	OE HIGH to High Z	7C166		7		8		8		10		12	ns
t <sub>LZCE</sub>	CE LOW to Low Z <sup>[7]</sup>		3		3		5		5		5		ns
t <sub>HZCE</sub>	CE HIGH to High Z <sup>[7, 8]</sup>			7		8		8		10		15	ns
t <sub>PU</sub>	CE LOW to Power-Up		0		0		0		0		0		ns
t <sub>PD</sub>	CE HIGH to Power-Dowr	า		12		15		20		20		20	ns
WRITE CYC	CLE <sup>[9]</sup>					•	•	•	•		•		
t <sub>WC</sub>	Write Cycle Time		12		15		20		20		25		ns
t <sub>SCE</sub>	CE LOW to Write End		8		12		15		20		25		ns
t <sub>AW</sub>	Address Set-Up to Write	End	9		12		15		20		25		ns
t <sub>HA</sub>	Address Hold from Write	End	0		0		0		0		0		ns
t <sub>SA</sub>	Address Set-Up to Write	Start	0		0		0		0		0		ns
t <sub>PWE</sub>	WE Pulse Width		8		12		15		15		20		ns
t <sub>SD</sub>	Data Set-Up to Write End		6		10		10		10		15		ns
t <sub>HD</sub>	Data Hold from Write End		0		0		0		0		0		ns
t <sub>LZWE</sub>	WE HIGH to Low Z <sup>[7]</sup>		3		5		5		5		5		ns
t <sub>HZWE</sub>	WE LOW to High Z <sup>[7,8]</sup>			6		7		7		7		10	ns

Shaded area contains advanced information.

Notes:

Test conditions assume signal transition time of 5 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V, and output loading of the specified I<sub>OL</sub>/I<sub>OH</sub> and 30-pF load capacitance.

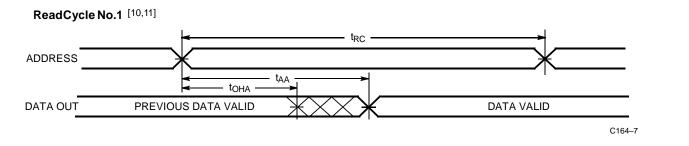
7. At any given temperature and voltage condition, t<sub>HZCE</sub> is less than t<sub>LZCE</sub> for any given device. These parameters are guaranteed by design and not 100% tested.

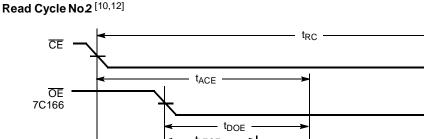
8. t<sub>HZCE</sub> and t<sub>HZWE</sub> are specified with C<sub>L</sub> = 5 pF as in part (b) in AC Test Loads. Transition is measured ±500 mV from steady-state voltage.

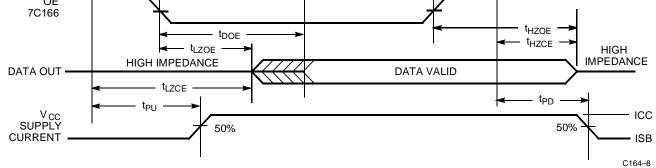
9. The internal write time of the memory is defined by the overlap of CE LOW and WE LOW. Both signals must be LOW to initiate a write and either signal can terminate a write by going HIGH. The data input set-up and hold timing should be referenced to the rising edge of the signal that terminates the write.

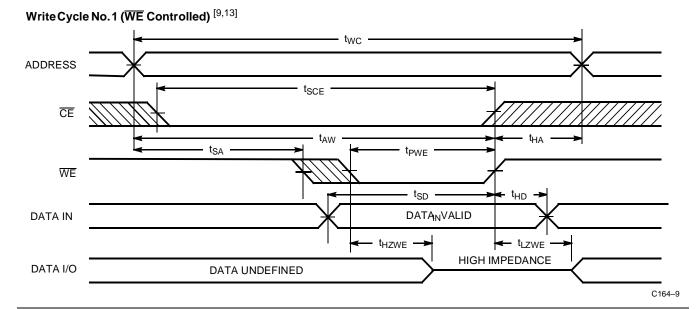


# **Switching Waveforms**









#### Notes:

 <sup>10.</sup> WE is HIGH for read cycle.

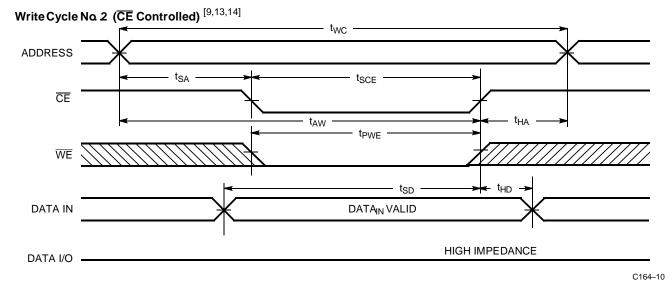
 11. Device is continuously selected,  $\overline{CE} = V_{IL}$ . (7C166:  $\overline{OE} = V_{IL}$  also).

 12. Address valid prior to or coincident with  $\overline{CE}$  transition LOW.

 13. 7C166 only: Data I/O will be high impedance if  $\overline{OE} = V_{IH}$ .



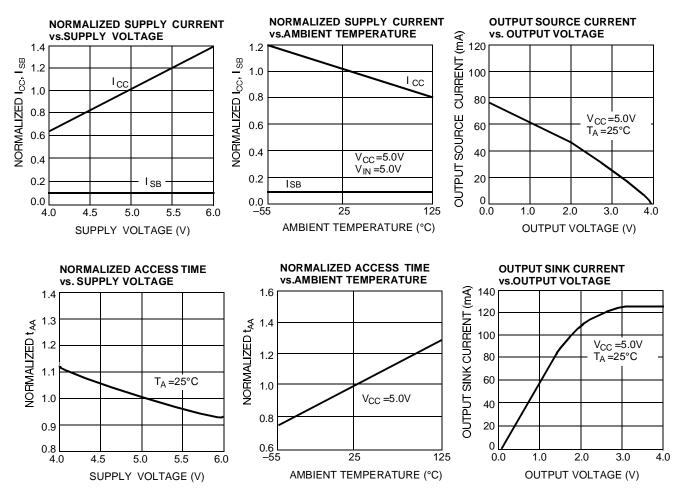
#### Switching Waveforms (Continued)



Note:

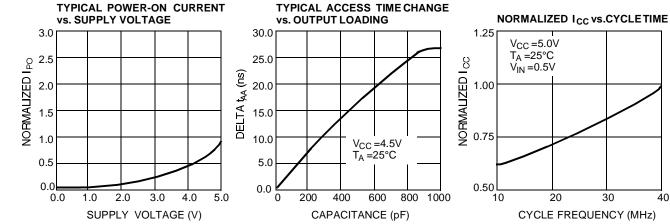
14. If CE goes HIGH simultaneously with WE HIGH, the output remains in a high-impedance state.

## **Typical DC and AC Characteristics**





# Typical DC and AC Characteristics (Continued)



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## CY7C164 Truth Table

CE	WE	Input/Output	Mode
Н	Х	High Z	Deselect/Power-Down
L	Н	Data Out	Read
L	L	Data In	Write

#### **Address Designators**

Address Name	Address Function	CY 7C164 Pin Number	CY7C166 Pin Number
A5	X3	1	1
A6	X4	2	2
A7	X5	3	3
A8	X6	4	4
A9	X7	5	5
A10	Y5	6	6
A11	Y4	7	7
A12	Y0	8	8
A13	Y1	9	9
A0	Y2	17	19
A1	Y3	18	20
A2	X0	19	21
A3	X1	20	22
A4	X2	21	23

#### CY7C166 Truth Table

CE	WE	OE	Input/Output	Mode
Н	Х	Х	High Z	Deselect/Power-Down
L	Н	L	Data Out	Read
L	L	Н	Data In	Write
L	Н	Н	High Z	Write



# **Ordering Information**

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
12	CY7C164-12PC	P9	22-Lead (300-Mil) Molded DIP	Commercial
	CY7C164-12VC	V13	24-Lead Molded SOJ	
15	CY7C164-15PC	P9	22-Lead (300-Mil) Molded DIP	Commercial
	CY7C164-15VC	V13	24-Lead Molded SOJ	-
20	CY7C164-20PC	P9	22-Lead (300-Mil) Molded DIP	Commercial
	CY7C164-20VC	V13	24-Lead Molded SOJ	-
25	CY7C164-25PC	P9	22-Lead (300-Mil) Molded DIP	Commercial
	CY7C164-25VC	V13	24-Lead Molded SOJ	
35	CY7C164-35PC	P9	22-Lead (300-Mil) Molded DIP	Commercial
	CY7C164-35VC	V13	24-Lead Molded SOJ	

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
12	CY7C166-12PC	P13	24-Lead (300-Mil) Molded DIP	Commercial
	CY7C166-12VC	V13	24-Lead Molded SOJ	
15	CY7C166-15PC	P13	24-Lead (300-Mil) Molded DIP	Commercial
	CY7C166-15VC	V13	24-Lead Molded SOJ	
20	CY7C166-20PC	P13	24-Lead (300-Mil) Molded DIP	Commercial
	CY7C166-20VC	V13	24-Lead Molded SOJ	
25	CY7C166-25PC	P13	24-Lead (300-Mil) Molded DIP	Commercial
	CY7C166-25VC	V13	24-Lead Molded SOJ	
35	CY7C166-35PC	P13	24-Lead (300-Mil) Molded DIP	Commercial
	CY7C166-35VC	V13	24-Lead Molded SOJ	]

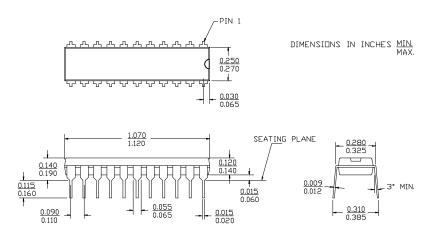
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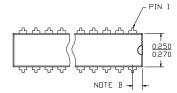
#### **Package Diagrams**

#### 22-Lead (300-Mil) Molded DIP P9

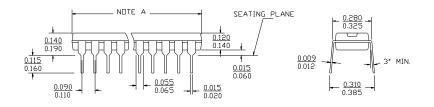


#### 24-Lead (300-Mil) Molded DIP P13/P13A

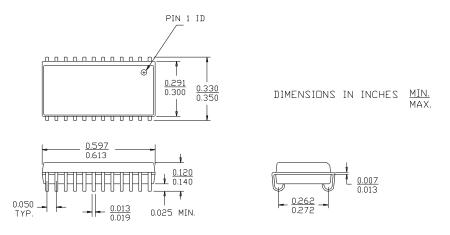
DIMENSIONS IN INCHES MIN.



	P 13	P 13A
NOTE A	<u>1.170</u> 1.200	<u>1.230</u> 1.260
NOTE B	<u>0.030</u> 0.050	<u>0.060</u> 0.080



24-Lead Molded SOJ V13



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